

LNPTTM THERMOCOMPTM COMPOUND KX97390

PDX-K-97390

DESCRIPTION

LNP THERMOCOMP KX97390 compound is based on POM (Acetal) copolymer resin containing 10% glass fiber.

GENERAL INFORMATION	
Features	High stiffness/Strength, No PFAS intentionally added
Fillers	Glass Fiber
Polymer Types	Acetal (POM) Copolymer
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Consumer	Sport/Leisure, Personal Accessory
Electrical and Electronics	Mobile Phone - Computer - Tablets
Industrial	Electrical

TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL ⁽¹⁾			
Tensile Stress, break	84	MPa	ASTM D638
Tensile Strain, break	3.2	%	ASTM D638
Tensile Modulus, 50 mm/min	4750	MPa	ASTM D638
Flexural Stress	124	MPa	ASTM D790
Flexural Modulus	4610	MPa	ASTM D790
Tensile Stress, break	86	MPa	ISO 527
Tensile Strain, break	3.4	%	ISO 527
Tensile Modulus, 1 mm/min	5400	MPa	ISO 527
Flexural Stress	137	MPa	ISO 178
Flexural Modulus	5400	MPa	ISO 178
IMPACT ⁽¹⁾			
Izod Impact, unnotched, 23°C	427	J/m	ASTM D4812
Izod Impact, notched, 23°C	48	J/m	ASTM D256
Multiaxial Impact	1	J	ISO 6603
Izod Impact, unnotched 80*10*4 +23°C	33	kJ/m ²	ISO 180/1U
Izod Impact, notched 80*10*4 +23°C	5	kJ/m ²	ISO 180/1A
THERMAL ⁽¹⁾			
HDT, 0.45 MPa, 3.2 mm, unannealed	164	°C	ASTM D648
HDT, 1.82 MPa, 3.2mm, unannealed	161	°C	ASTM D648
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	161	°C	ISO 75/Af
PHYSICAL ⁽¹⁾			
Density	1.45	g/cm ³	ASTM D792

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
Moisture Absorption, (23°C/50% RH/24 hrs)	0.1	%	ASTM D570
Mold Shrinkage, flow, 24 hrs ⁽²⁾	1.2	%	ASTM D955
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	1.3	%	ASTM D955
Mold Shrinkage, flow, 24 hrs ⁽²⁾	1.16	%	ISO 294
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	1.24	%	ISO 294
Density	1.45	g/cm ³	ISO 1183
Moisture Absorption (23°C / 50% RH)	0.35	%	ISO 62
INJECTION MOLDING ⁽³⁾			
Drying Temperature	80	°C	
Drying Time	4	Hrs	
Melt Temperature	200 – 215	°C	
Front - Zone 3 Temperature	210 – 220	°C	
Middle - Zone 2 Temperature	195 – 205	°C	
Rear - Zone 1 Temperature	175 – 190	°C	
Mold Temperature	80 – 110	°C	
Back Pressure	0.2 – 0.3	MPa	
Screw Speed	30 – 60	rpm	

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (3) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

ADDITIONAL PRODUCT NOTES

No PFAS intentionally added: The grade listed in this document does not contain PFAS intentionally added during Seller's manufacturing process and is not expected to contain unintentional PFAS impurities. Each user is responsible for evaluating the presence of unintentional PFAS impurities.

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